

东睦科达 NBTM KEDA

MOLDED POWER INDUCTORS





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浙江东睦科达磁电有限公司

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2000 0 成立时间

600114

浙江东睦科达磁电有限公司(KDM)创建于2000年,现为东睦新材料集团股份有限公司(股票代码:600114)的全资子公司。

东睦科达是全球屈指可数的软磁材料及制品生产商,长期致力于 高性能低损耗软磁合金粉末的研发和生产。近年来,随着AI智能技术的 发展,电感元件需求量快速增长。为适应未来电源设计小型化、大电流、 高能效的发展趋势,科达推出铜铁共烧一体电感。产品主要应用于GPU、 AI服务器、自动驾驶、消费电子等领域。 Founded in 2000, ZHEJIANG NBTM KEDA MAGNETOELECTRICITY CO., LTD. (KDM) now is a wholly-owned subsidiary of NBTM New Material Group Co., Ltd. (Stock Code: 600114).

NBTM KEDA is one of the few global manufacturers of soft magnetic materials and products, dedicated to high performance for a long timeResearch and production of low loss soft magnetic alloy powder. In recent years, with the development of AI intelligent technology, The demand for inductive components is rapidly increasing. To adapt to the miniaturization, high current, and high energy efficiency of future power supply designs In response to the development trend, Keda has launched a copper iron co fired integrated inductor. The product is mainly used for GPU and AI services Industries such as robotics, autonomous driving, and consumer electronics.







Features

Low DC resistance

High saturation current

Low loss at high frequency

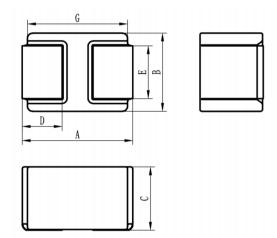
High reliability

EMI resistance

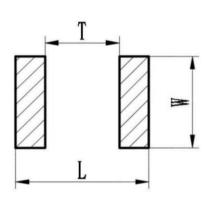
operating temperature:-40~125°C



Dimensions



Recommend PCB Pattern [unit : mm]



| Series | А | В | С | D | Е | G | L | Т | W |
|-------------|--------------|-------------|-------------|-------------|-------------|--------------|------|-----|-----|
| KMLS070540 | 6.8 ±0.2 | 4.8 ±0.2 | 3.8 ±0.2 | 2.2 ±0.2 | 3.6 ±0.2 | 6.2 ±0.2 | 7.2 | 2.2 | 3.8 |
| KMLS070530A | 7.0 ±0.2 | 5.0 ±0.2 | 2.8 ±0.2 | 2.2 ±0.2 | 3.0 ±0.2 | 6.4 ±0.2 | 7.2 | 2.0 | 3.2 |
| KMLS130825 | 13.0 ±0.4 | 8.0 ±0.2 | 2.3 ±0.2 | 2.5 ±0.3 | 3.5 ±0.3 | 12.6 ±0.2 | 13.5 | 7.0 | 3.8 |
| KMLS130840 | 13.0 ±0.4 | 8.0 ±0.2 | 3.8 ±0.2 | 2.5 ±0.3 | 3.5 ±0.3 | 12.6 ±0.2 | 13.5 | 7.0 | 3.8 |



Electrical Specifications

| Part No. | L0(nH) @1MHz,1V | DCR(mΩ) @25°C | Isat(A) Typ. | Irms(A) Typ. |
|-----------------|--------------------|------------------|-----------------|-----------------|
| KMLS070540R12M | 120±20% | 0.25Max. | 45 | 45 |
| KMLS070530AR10M | 100±20% | 0.27Max. | 50 | 50 |
| KMLS130825R15M | 150±20% | 0.45Max. | 50 | 60 |
| KMLS130840R22M | 220±20% | 0.48Max. | 63 | 55 |

- All tests should be conducted at room temperature(25 ± 5°C);
- Isat: DC current that causes L0 to drop approximately 30%;
- Irms: DC current that causes a temperature rise less than 40°C.PCB land pattern, trace sizeand other cooling provision will affect the part temperature. Therefore temperature rise should be verified in application conditions. The part temperature (ambient + temp. rise) should not exceed 125°C under worst case operating conditions.









Features

Low DC resistance

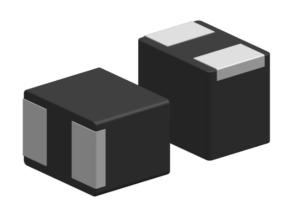
High saturation current

Low loss at high frequency

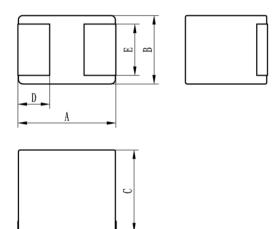
High reliability

EMI resistance

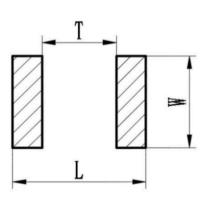
operating temperature:-40~125°C



Dimensions [unit:mm]



Recommend PCB Pattern [unit : mm]



| Series | А | В | С | D | Е | L | Т | W |
|------------|-------------|--------------|--------------|-------------|-------------|-----|-----|-----|
| KMBS070560 | 6.8 ±0.2 | 4. 8 ±0.2 | 5. 8 ±0.2 | 2.2 ±0.2 | 3.6 ±0.2 | 7.2 | 2.2 | 3.8 |



Electrical Specifications

| Part No. | L0(nH) | DCR(mΩ) | Isat(A) | Irms(A) |
|----------------|----------|----------|---------|---------|
| | @1MHz,1V | @25°C | Typ. | Typ. |
| KMBS070560R10M | 100±20% | 0.16Max. | 75 | 55 |

- All tests should be conducted at room temperature (25 ± 5°C);
- Isat: DC current that causes L0 to drop approximately 30%;
- Irms: DC current that causes a temperature rise less than 40°C.PCB land pattern, trace size and other cooling provision will affect the part temperature. Therefore temperature rise should be verified in application conditions. The part temperature (ambient + temp. rise) should not exceed 125°C under worst case operating conditions.









Features

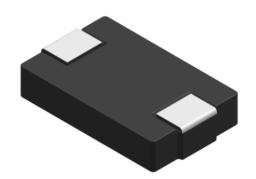
Low DC resistance

Low loss at high frequency

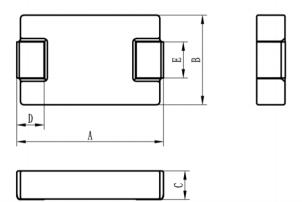
High reliability

EMI resistance

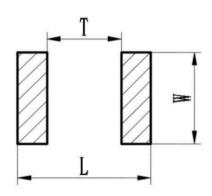
Stability across wide temperature range operating temperature:-40~125°C



Dimensions [unit : mm]



Recommend PCB Pattern [unit : mm]



| Series | А | В | С | D | Е | L | Т | W |
|------------|--------------|--------------|-------------|-------------|-------------|------|-----|-----|
| KGLS130825 | 13.0 ±0.4 | 8. 0 ±0.2 | 2.3 ±0.2 | 2.5 ±0.3 | 3.5 ±0.3 | 13.5 | 7.0 | 3.8 |
| KGLS130840 | 13.0 ±0.4 | 8. 0 ±0.2 | 3.8 ±0.2 | 2.5 ±0.3 | 3.5 ±0.3 | 13.5 | 7.0 | 3.8 |



Electrical Specifications

| Part No. | L0(nH) @1MHz,1V | DCR(mΩ) @25°C | Isat(A) Typ. | Irms(A) Typ. |
|----------------|--------------------|------------------|-----------------|-----------------|
| KGLS130825R12M | 120±20% | 0.45Max. | 35 | 55 |
| KGLS130840R15M | 150±20% | 0.48Max. | 40 | 55 |

- All tests should be conducted at room temperature (25 ± 5°C);
- Isat: DC current that causes L0 to drop approximately 30%;
- Irms: DC current that causes a temperature rise less than 40°C.PCB land pattern, trace size and other cooling provision will affect the part temperature. Therefore temperature rise should be verified in application conditions. The part temperature (ambient + temp. rise) should not exceed 125°C under worst case operating conditions.











Q200

Features

Multiple currents

High saturation current

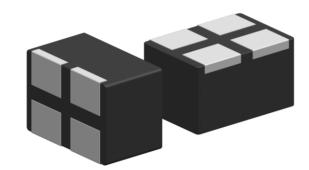
Low DC resistance

Low loss at high frequency

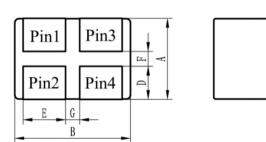
High reliability

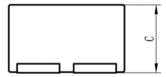
EMI resistance

operating temperature:-40~125°C

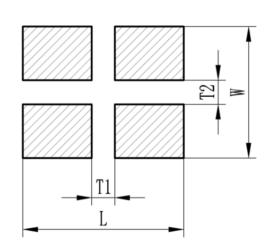


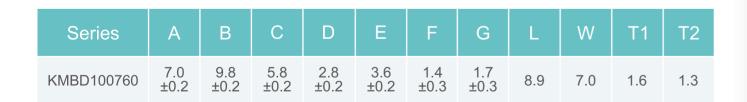
Dimensions [unit:mm]





Recommend PCB Pattern







Electrical Specifications

| Part No. | L0(nH) | DCR(mΩ) | Isat(A) | Irms(A) |
|----------------|----------|----------|---------|---------|
| | @1MHz,1V | @25°C | Typ. | Typ. |
| KMBD10076085NM | 85±20% | 0.16Max. | 88 | 60 |

- All tests should be conducted at room temperature (25 ± 5°C);
- Isat: DC current that causes L0 to drop approximately 30%;
- Irms: DC current that causes a temperature rise less than 40°C.PCB land pattern, trace size and other cooling provision will affect the part temperature. Therefore temperature rise should be verified in application conditions. The part temperature (ambient + temp. rise) should not exceed 125°C under worst case operating conditions.
- All specifications are for single phase(Pin1 to Pin2 or Pin3 to Pin4).

